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/*
* Copyright (c) 2015-2018 in2H2 inc.
* System developed for in2H2 inc. by Intermotion Technology, Inc.
*
* Full system RTL, C sources and board design files available at https://github.com/nearist
*
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* Tecno77 S.r.l. Team Members:
* - Stefano Aldrigo, Board Layout Design
*
* We dedicate this project to the memory of Bruce McCormick, an AI pioneer
* and advocate, a good friend and father.
*
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LAYER	DEFINITION	DESCRIPTION	THICKNESS (um)	THICKNESS (mils)
coating		GREEN SOLDER M.	12,7	0,500
TOP	SIGNAL	COPPER	35	1,378
substrate		DIELECTRIC FR4	132	5,197
L2	PLANE LAYER - PWR	COPPER	35	1,378
substrate		DIELECTRIC FR4	1200	47,244
L3	PLANE LAYER - GND	COPPER	35	1,378
substrate		DIELECTRIC FR4	132	5,197
BTM	SIGNAL	COPPER	35	1,378
coating		GREEN SOLDER M.	12,7	0,500
Total Thick.			1629	64,150